RECOMMENDATIONS AND GUIDELINES

WIRE BONDING

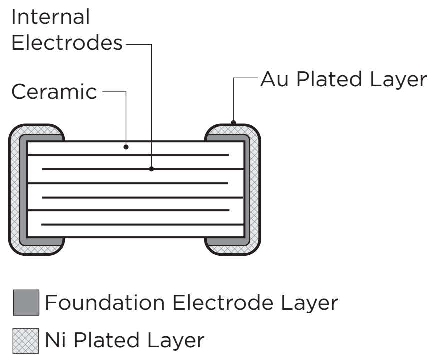
- Gold Wire: 25μm (0.001 inch) diameter

BONDING

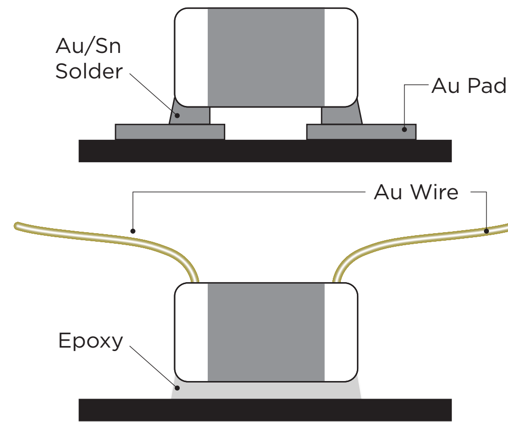
- Thermo compression, ultrasonic ball bonding
- Required stage temperature: 150˚C to 200˚C
- Required wedge or capillary weight: 0.2N to 0.5N
- Bond the capacitor and base substrate or other devices with gold wire

FEATURES

- Designed specifically for wire bonding and application of gold-tin (AuSN) solder*
- Ideal for mounting in packages, such as optical communication related devices, IC, etc.
- Contributes to miniaturization of the set



STRUCTURE EXAMPLE



MOUNTING EXAMPLE

* This product is suitable only for wire bonding or use of gold-tin (AuSn) solder. Other mounting methods **should not** be used.